

# SOT2130-1

LFBGA400, low profile fine-pitch ball grid array; 400 bumps;  
0.8 mm pitch; 17 mm x 17 mm x 1.63 mm body

28 February 2022

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA400
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-12-2021
<b>Manufacturer package code</b>	98ASA01736D

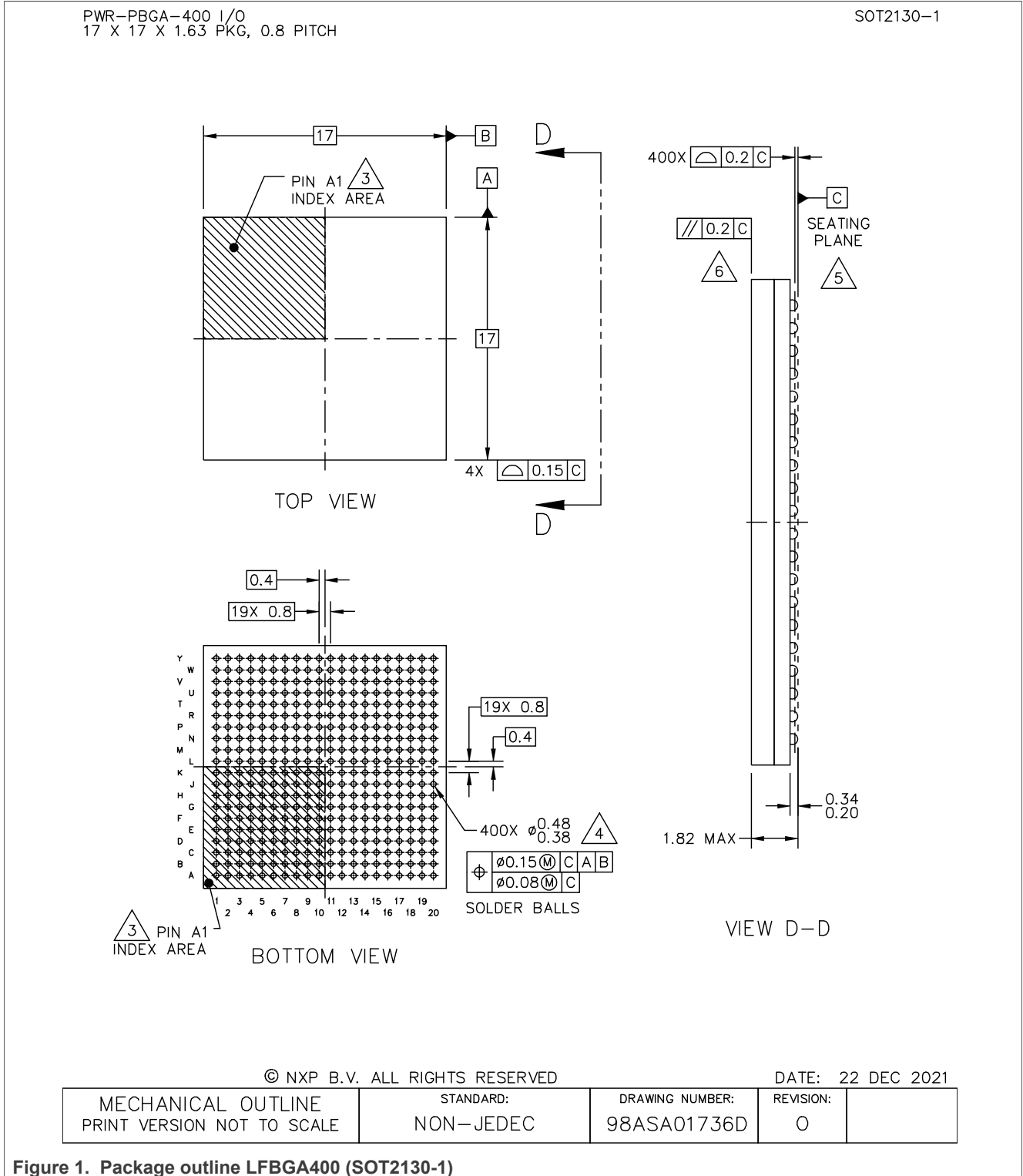
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.63	1.82	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	400	-	



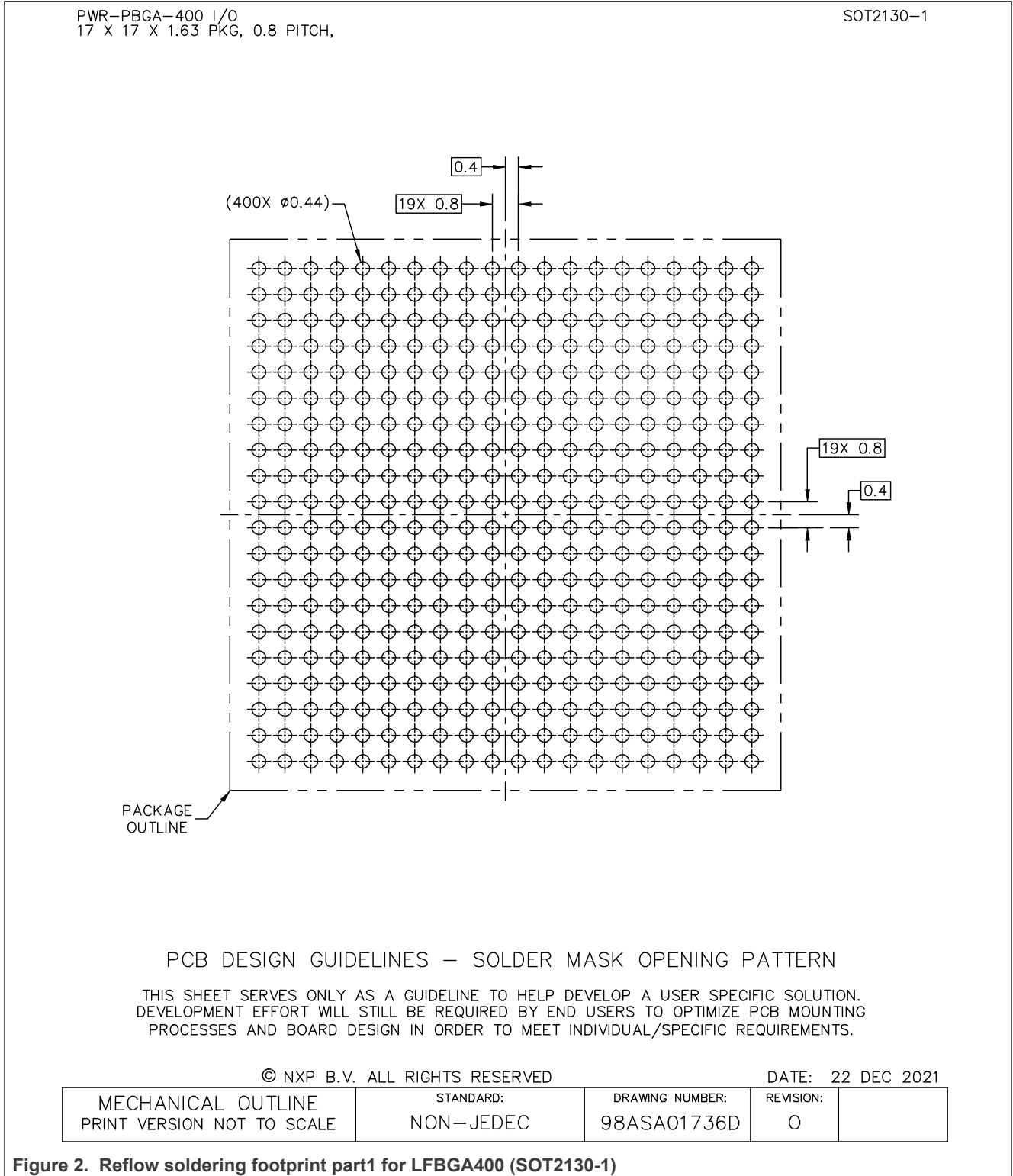
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2 Package outline



LFBGA400, low profile fine-pitch ball grid array; 400 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.63 mm body

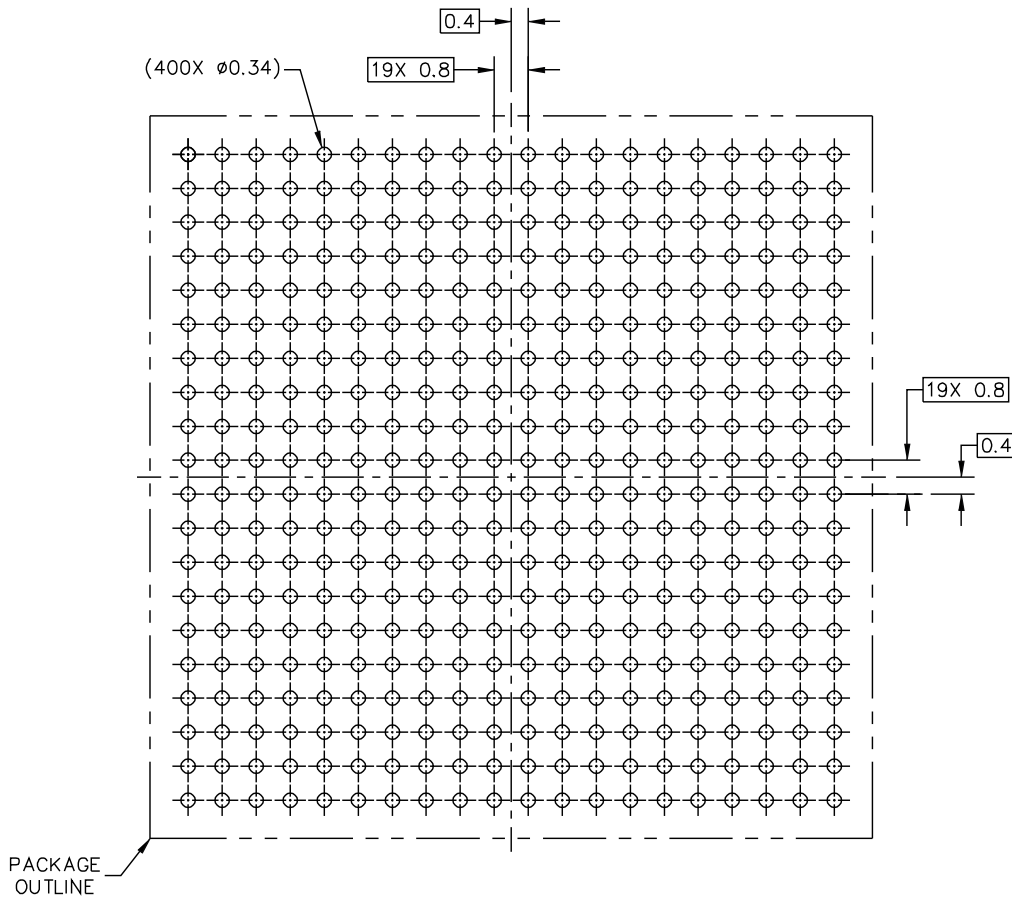
3 Soldering



LFBGA400, low profile fine-pitch ball grid array; 400 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.63 mm body

PWR-PBGA-400 I/O  
17 X 17 X 1.63 PKG, 0.8 PITCH,

SOT2130-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

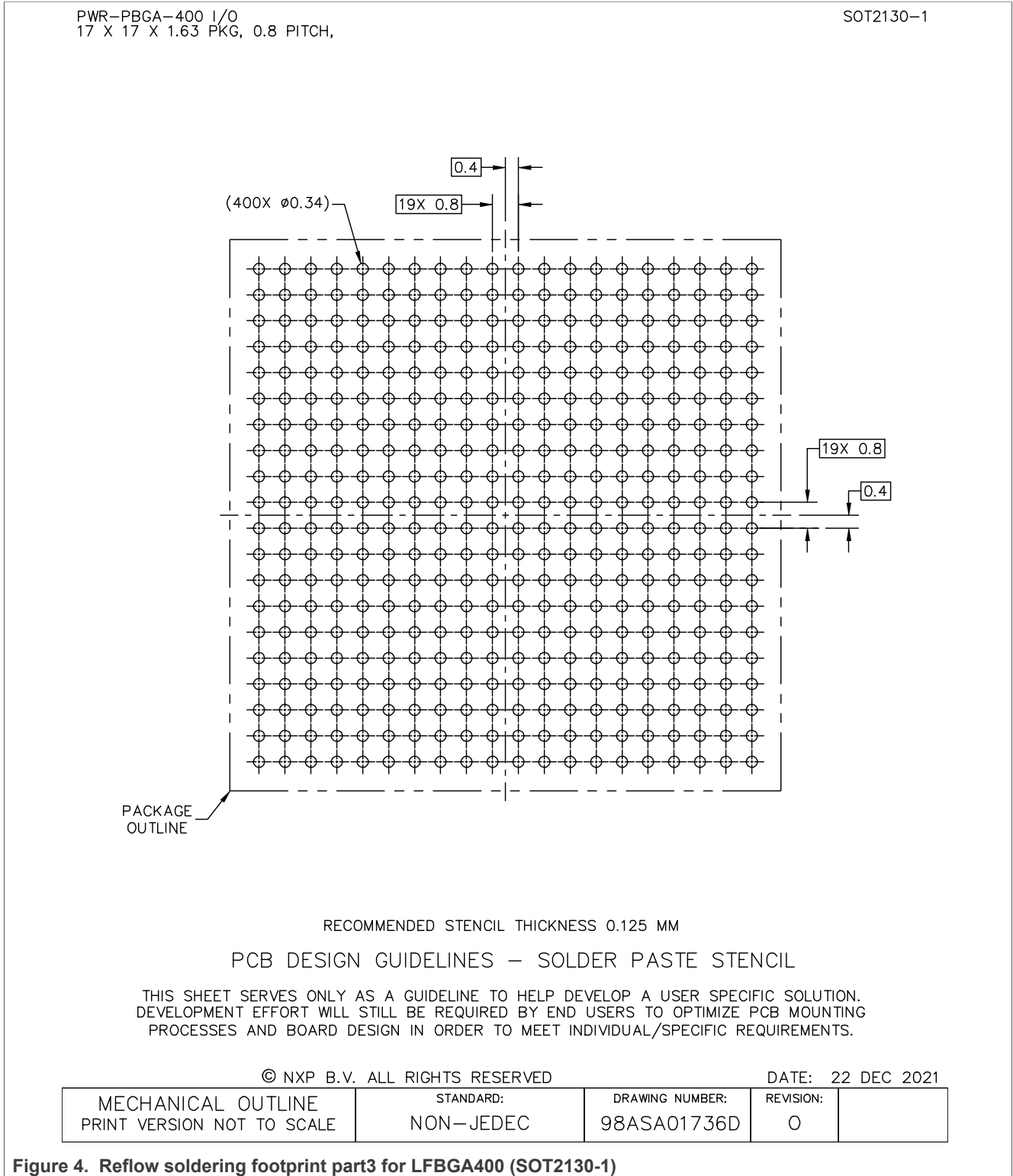
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DATE: 22 DEC 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01736D	REVISION: 0
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Figure 3. Reflow soldering footprint part2 for LFBGA400 (SOT2130-1)

LFBGA400, low profile fine-pitch ball grid array; 400 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.63 mm body



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PWR-PBGA-400 I/O  
17 X 17 X 1.63 PKG, 0.8 PITCH

SOT2130-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note LFBGA400 (SOT2130-1)

## 4 Legal information

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